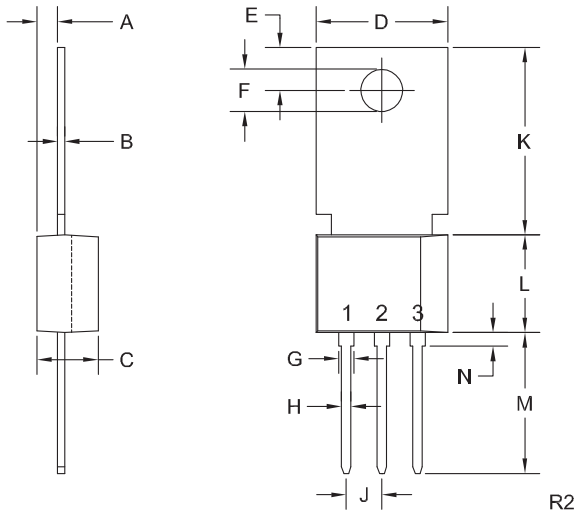


Package Details

TO-202 Case



Mechanical Drawing



| SYMBOL | DIMENSIONS | | | |
|---------|------------|-------|-------------|-------|
| | INCHES | | MILLIMETERS | |
| | MIN | MAX | MIN | MAX |
| A | 0.055 | 0.071 | 1.40 | 1.80 |
| B | 0.016 | 0.024 | 0.40 | 0.60 |
| C | 0.173 | 0.181 | 4.40 | 4.60 |
| D | 0.374 | 0.413 | 9.50 | 10.5 |
| E | 0.118 | 0.154 | 3.00 | 3.90 |
| F (DIA) | 0.124 | 0.150 | 3.15 | 3.80 |
| G | 0.035 | 0.055 | 0.90 | 1.40 |
| H | 0.023 | 0.031 | 0.59 | 0.80 |
| J | 0.094 | 0.106 | 2.39 | 2.69 |
| K | 0.459 | 0.559 | 11.66 | 14.21 |
| L | 0.280 | 0.346 | 7.12 | 8.80 |
| M | 0.406 | 0.531 | 10.3 | 13.5 |
| N | 0.024 | 0.059 | 0.60 | 1.50 |

TO-202 (REV: R2)

Lead Code:

TRIAC

- 1) MT1
- 2) MT2
- 3) Gate

SCR

- 1) Cathode
- 2) Anode
- 3) Gate

Packing Options

Bulk:

White corrugated box with static shielded bags

Bulk Packing Quantity: 500

R0 (26-November 2013)

Material Composition Specification

TO-202 Case



Device average mass 1438 mg
 Fluctuation margin +/-10%

| Component | Material | Material | | Substance | CAS No. | Substance | | |
|-----------------|--------------------------------|------------------|-------|--------------------------------|-------------|-----------|--------|---------|
| | | (%wt) | (mg) | | | (%wt) | (mg) | (ppm) |
| active device | doped Si | 0.08% | 1.2 | Si | 7440-21-3 | 0.083% | 1.2 | 834 |
| bond wire* | aluminum | 0.28% | 4 | Al | 7429-90-5 | 0.278% | 4 | 2,782 |
| leadframe | Cu alloy 194 w/ silver plating | 56.68% | 815 | Cu | 7440-50-8 | 55.216% | 794 | 552,156 |
| | | | | Fe | 7439-89-6 | 1.307% | 18.8 | 13,074 |
| | | | | Zn | 7440-66-6 | 0.07% | 1 | 695 |
| | | | | P | 7723-14-0 | 0.056% | 0.8 | 556 |
| | | | | Ag | 7440-22-4 | 0.028% | 0.4 | 278 |
| encapsulation** | EMC | 40.82% | 587 | silica | 7631-86-9 | 29.798% | 428.5 | 297,983 |
| | | | | epoxy resin | Proprietary | 9.388% | 135 | 93,880 |
| | | | | Sb ₂ O ₃ | 1309-64-4 | 0.817% | 11.75 | 8,171 |
| | | | | TBBA | 79-94-7 | 0.817% | 11.75 | 8,171 |
| | EMC GREEN | 40.82% | 587 | silica (fused) | 60676-86-0 | 34.701% | 499 | 347,010 |
| | | | | epoxy resin | Proprietary | 2.594% | 37.3 | 25,939 |
| | | | | phenol resin | 9003-35-4 | 2.594% | 37.3 | 25,939 |
| | | | | epoxy, cresol novolac | 29690-82-2 | 0.814% | 11.7 | 8,136 |
| | | | | carbon black | 1333-86-4 | 0.118% | 1.7 | 1,182 |
| | plating*** | tin/lead process | 2.14% | 30.8 | Sn | 7440-31-5 | 1.711% | 24.6 |
| Pb | | | | | 7439-92-1 | 0.431% | 6.2 | 4,312 |
| matte tin | | 2.14% | 30.8 | Sn | 7440-31-5 | 2.142% | 30.8 | 21,419 |

*Part number CEN-U95 uses gold bond wires:

| | | | | | | | | |
|-----------|------|-------|---|----|-----------|--------|---|-------|
| bond wire | gold | 0.28% | 4 | Au | 7440-57-5 | 0.278% | 4 | 2,782 |
|-----------|------|-------|---|----|-----------|--------|---|-------|

**EMC GREEN molding compound is Halogen-Free.

***For Lead Free plating, add suffix "PB FREE" to part number.

For Tin/Lead plating, add suffix "TIN/LEAD" to part number.

No suffix designation allows for the supply of either lead-free or tin/lead plated product depending on availability.

Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R3 (12-June 2018)